

SOT258-2

ceramic pin grid array package; 84 pins; body 27.9 x 27.9 x 2.3 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	CPGA84
Package type industry code	CPGA84
Package style descriptive code	CPGA (ceramic pin grid array)
Package style suffix code	NA (not applicable)
Package body material type	C (ceramic)
Mounting method type	T (through-hole mount)
Issue date	1-11-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.43	-	27.9	28.45	mm
E	package width	27.43	-	27.9	28.45	mm
A ₂	package height	2.03	-	2.3	2.54	mm
n ₂	actual quantity of termination	-	-	84	-	



2. Package outline

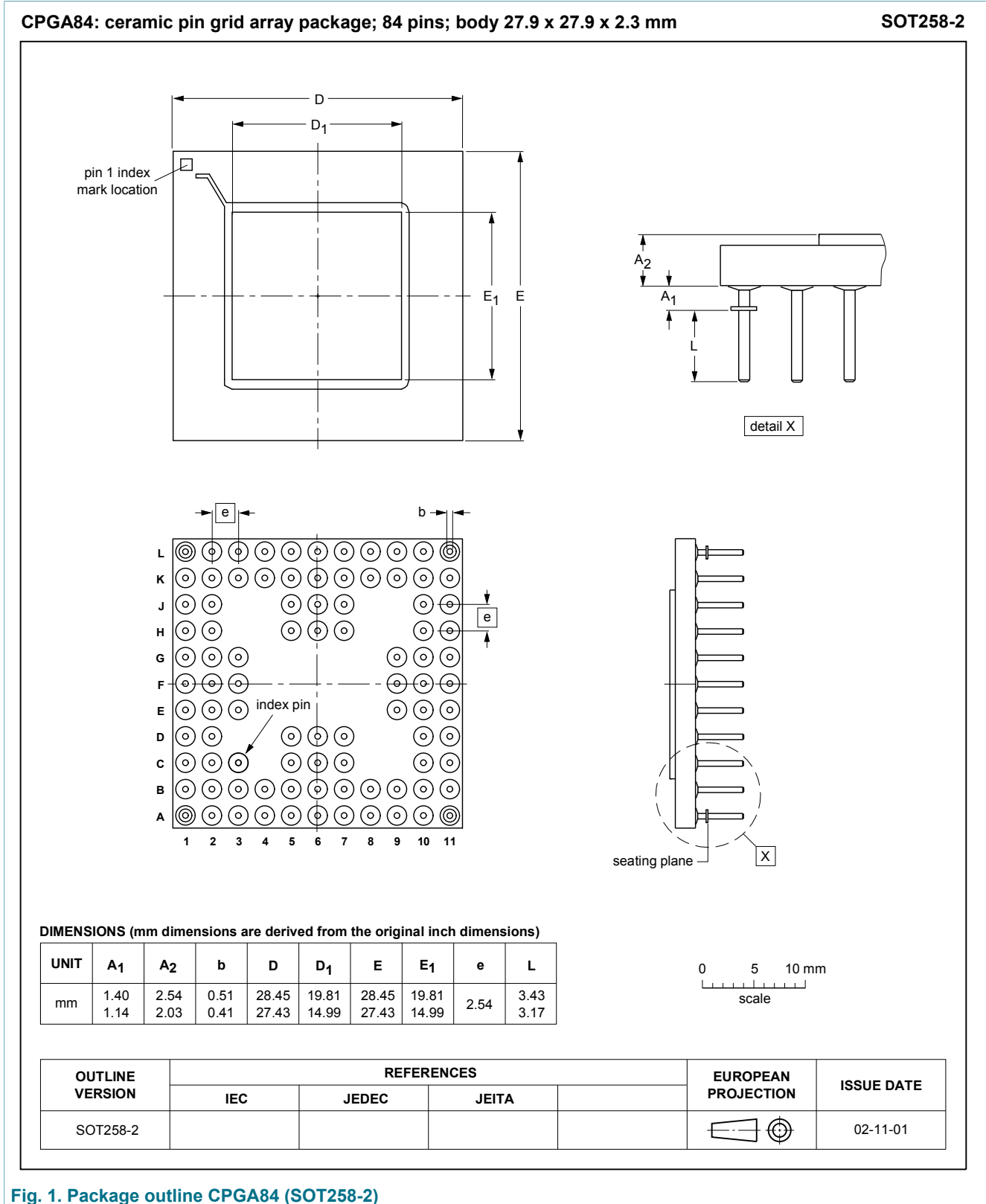


Fig. 1. Package outline CPGA84 (SOT258-2)

3. Legal information

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